

## PRESS RELEASE

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### RoodMicrotec Gains EUR 5 Million in New Contracts

**RoodMicrotec**, the Dutch supplier of semiconductors and advanced microchips, has secured two significant new contracts which are expected to increase its forward order book by at least EUR 5.0 million spread over the next 10 years. The company expects to book EUR 4.5 million in orders with an industrial and automotive client, and is to be allocated EUR 850,000 of EU and German public funds for a joint technology project, out to 2019.

The new supply chain management (SCM) contract signed by **RoodMicrotec** with a German automotive and industrial client will start in early 2017 with an initial order of EUR 100,000, due to be completed by the end of the year. Subsequent orders are expected to generate at least EUR 4.4 million in additional revenue over 10-years.

**Reinhard Pusch, RoodMicrotec COO**, said: *“Because the application we are developing for this German SCM order will also be utilised with other systems and designs, we expect it to result in organic growth in the company’s turnover.”*

**RoodMicrotec** has also been allocated EUR 850,000 in public funding over the next three years, approved by the ECSEL Joint Undertaking, a public/private partnership for the development of the European electronic components and systems industry. The organisation has granted a total of EUR 7.2 million in EU funding for the EuroPAT-MASIP project, for which **RoodMicrotec** is one of the 27 submitting partners. The proposed project was deemed to make a significant contribution to European competitiveness and job creation in the electronics industry.

**Bert De Colvenaer, Executive Director at the ECSEL JU**, said: *“These projects represent the very top of industrial and academic excellence in Europe in our field. We’re convinced that this decision is another milestone for Europe in achieving our shared goals in the electronic components and systems sector.”*

The funded project involves the development of ASICs (Application Specific Integrated Circuits) for a MEMS gyroscope, for an image sensor, and for a Radio Frequency (RF) ASIC. Through its participation in the project, **RoodMicrotec** will be able to refine its existing expertise in all three areas.

**Reinhard Pusch, RoodMicrotec COO** concluded: *“Both these projects will enable RoodMicrotec to take the development of its ASIC supply chain management expertise to a new level. The public recognition that the company has a valuable contribution to make to the growth and competitiveness of the European electronics industry as a whole, is also a strong endorsement of the quality of the services we offer to the market.”*

**ENDS**

**About ECSEL JU:**

ECSEL JU (Electronic Components and Systems European Leadership Joint Undertaking) is a partnership between the private and the public sectors for electronic components and systems.

Electronic components and systems (ECS) are a pervasive Key Enabling Technology, impacting all industrial branches and almost all aspects of life. A smartphone, a smart card, a smart energy grid, a smart city, even smart governance; everything “smart” is based on integrating semiconductor chips running embedded software. They provide the fabric on which the internet runs; they give life to portable phones and tablets; they drive driverless cars and trains, fly airliners, drones and satellites. In modern times, no national economy can win in the global competition without mastering this technology, with unparalleled systemic and strategic impact.

**About EuroPAT-MASIP:**

EuroPAT-MASIP (European Packaging Assembly and Test pilot for Manufacturing of Advanced System in Package) is a project submitted to ECSEL JU for European Funding. Partners of the submitted project are:

3DiS Technologies, Advanced Vacuum Distribution Europe AB, Afore Oy, AMIC Angewandte Micro Messtechnik GmbH, Berliner Nanotest und Design GmbH, BESI Austria GmbH, BESI Netherlands BV, Commissariat al Energie Atomique et aux Energies Alternatives, Connaught Electronics Limited, ELMOS Semiconductor AG, EV Group E. Thallner GmbH, Fraunhofer Gesellschaft zur Förderung der angewandten Forschung e.V., INNOSENT GmbH, KETEK, micro analog systems Oy, MURATA Electronics Oy, Nanium S.A., Nokian Tyres plc., NXP Semiconductors France SAS, PAC TECH Packaging Technologies GmbH, Packaging SIP, RoodMicrotec GmbH, Semilab Felvezeto Fizikal Laboratorium Reszvenytarsasag, SENCIO BV, Silicon Radar GmbH, Spinverse Innovation Management Oy, Teknologian tutkimuskeskus VTT Oy, TexEDA Design GmbH

**About RoodMicrotec**

With more than 45 years’ experience as an independent value-added service provider in the area of micro and optoelectronics, RoodMicrotec offers Fabless Companies, OEMs and other companies a one-stop shop proposition. With its *powerful solutions* RoodMicrotec has built up a strong position in Europe.

Our services comply with the industrial and quality requirements of the high reliability/space, automotive, telecommunications, medical, industrial and electronics sectors.

*Certified by RoodMicrotec* concerns inter alia certification of products to the stringent ISO/TS 16949 standard that applies to suppliers to the automotive industry. The company also has an accredited laboratory for test activities and qualification to the ISO/IEC 17025 standard.

Its value-added services include (eXtended) supply chain management and total manufacturing solutions with partners, failure & technology analysis, qualification & burn-in, test & product engineering, production test (including device programming and end-of-line service), ESD/ESDFOS assessment & training and quality & reliability consulting.

RoodMicrotec has branches in Germany (Dresden, Nördlingen, Stuttgart), United Kingdom (Bath) and the Netherlands (Zwolle).

For more information visit <http://www.roodmicrotec.com>

#### **Further information**

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